

					Base	Processed	Copper		
Laye	er	Stack up	Description	Туре	Thickness	Thickness	Coverage	εг	εr
			Taiyo PSR 4000	SolderMask		2.000		4.000	000
1	↑		Copper Foil 12 microns	Copper	0.472	1.850	0.000		
			Iteq IT180A Prepreg 106	Dielectric	3.100	1.848		3.570	570
			Iteq IT180A Prepreg 106	Dielectric	3.100	1.848		3.570	570
2							60.000		
3			Iteq IT180A 5 mil core 1/1	FR4		5.000	30.000	4.050	050
3			. IT1004 D 0110	D: 1				0.000	000
			Iteq IT180A Prepreg 2113	Dielectric		3.553		3.880	
			Iteq IT180A Prepreg 2113	Dielectric		3.553		3.880	
			Iteq IT180A Prepreg 2113	Dielectric	5.015	3.553		3.880	880
4	97						60.000		
5	61.9		IT 180A 12 mil core 1/1	FR4		12.000 1.260	60.000	4.230	230
3			Itog IT190A Droprog 2112	Diologtrio		3.553		3.880	990
		1 10 10 10 10 10 10 10 10 10 10 10 10 10	Iteq IT180A Prepreg 2113	Dielectric					
			Iteq IT180A Prepreg 2113	Dielectric		3.553		3.880	
			Iteq IT180A Prepreg 2113	Dielectric		3.553		3.880	880
6			II. IT1004 F II. 1/1	ED.4			30.000	4.050	050
7			Iteq IT180A 5 mil core 1/1	FR4		5.000 1.260	60.000	4.050	050
,			Iteq IT180A Prepreg 106	Dielectric		1.848		3.570	570
	1								
_			Iteq IT180A Prepreg 106	Dielectric		1.848		3.570	3/0
8	▼		Copper Foil 12 microns	Copper			0.000		
			Taiyo PSR 4000	SolderMask		2.000		4.000	000

Copper Thickness = 11.260 | Dielectric Thickness = 50.711 | Solder Mask Thickness = 4.000 | Stack Up Thickness = 61.970 | Stack Up Thickness with Soldermask = 65.970 | Stack Up Cost = 0.00 |

Impedance ID	Impedance Signal Layer	Structure Name	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance		Tol (+/- %)
1	1	Coated Microstrip 1B	2	0	6.069	0.000	0.000	50.000	50.000	10.000
2	1	Edge Coupled Coated Microstrip 1B	2	0	5.000	5.400	0.000	90.110	90.000	10.000
3	1	Edge Coupled Coated Microstrip 1B	2	0	4.000	6.000	0.000	100.030	100.000	10.000
4	3	Offset Stripline 1B1A	2	4	5.529	0.000	0.000	50.000	50.000	10.000
5	3	Edge Coupled Offset Stripline 1B1A	2	4	5.000	5.900	0.000	90.070	90.000	10.000
6	3	Edge Coupled Offset Stripline 1B1A	2	4	4.000	6.550	0.000	100.020	100.000	10.000
7	6	Offset Stripline 1B1A	5	7	5.529	0.000	0.000	50.000	50.000	10.000
8	6	Edge Coupled Offset Stripline 1B1A	5	7	5.000	5.900	0.000	90.070	90.000	10.000
9	6	Edge Coupled Offset Stripline 1B1A	5	7	4.000	6.550	0.000	100.020	100.000	10.000
10	8	Coated Microstrip 1B	7	0	6.069	0.000	0.000	50.000	50.000	10.000
11	8	Edge Coupled Coated Microstrip 1B	7	0	5.000	5.400	0.000	90.110	90.000	10.000

StackName: smile-15000-3-rev1.6	Version:	Revision:	Modification:	Date of Revision:	Editor		
Date: 20:00:2010	Associated Documents:					_	
Author:	CAM No: F25062k16-32657					Page 1/2	
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Site:							

Units: Mils



Impedan	Impedance e Signal Layer	Structure Name	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer		Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance		Tol (+/- %)
12	8	Edge Coupled Coated Microstrip 1B	7	0	4.000	6.000	0.000	100.030	100.000	10.000

<u>Notes</u>

StackName: smile-15000-3-rev1.6	Version:	Revision:	Modification:	Date of Revision:	Editor	
Date: 28.06.2016	Associated Documents:					
Author:	CAM No: F25062k16-32657					Page 2/2
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Site:						